

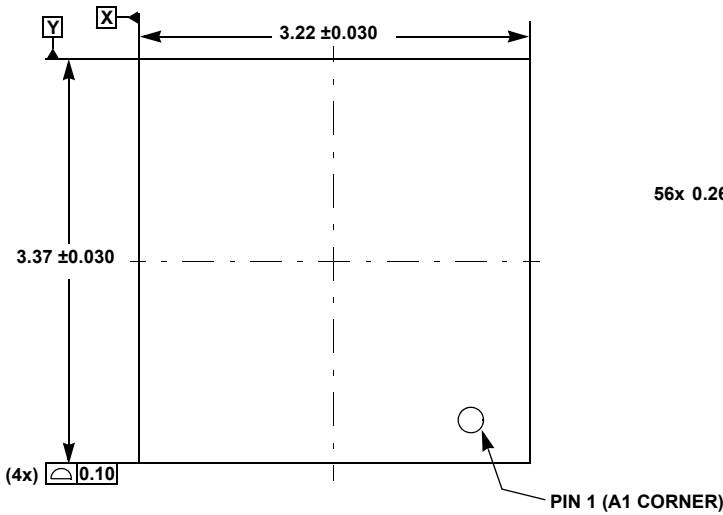
Plastic Packages for Integrated Circuits

Package Outline Drawing

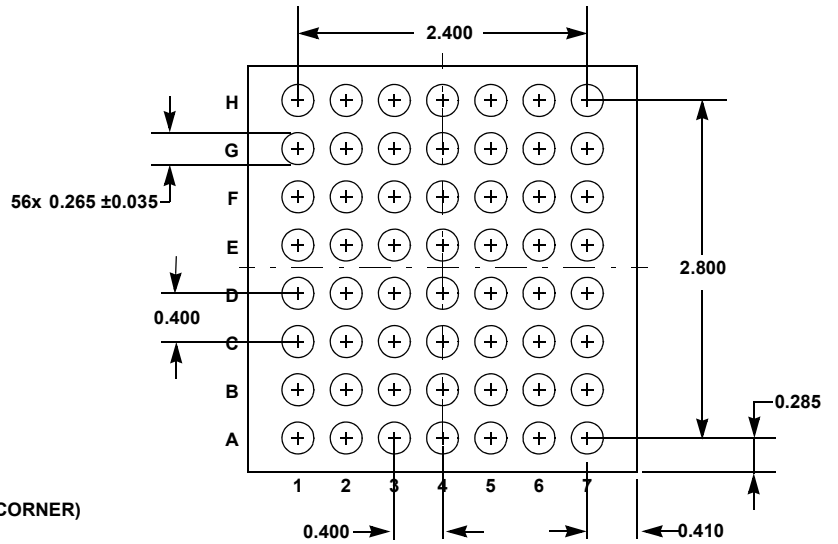
W7x8.56A

56 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.4mm Pitch)

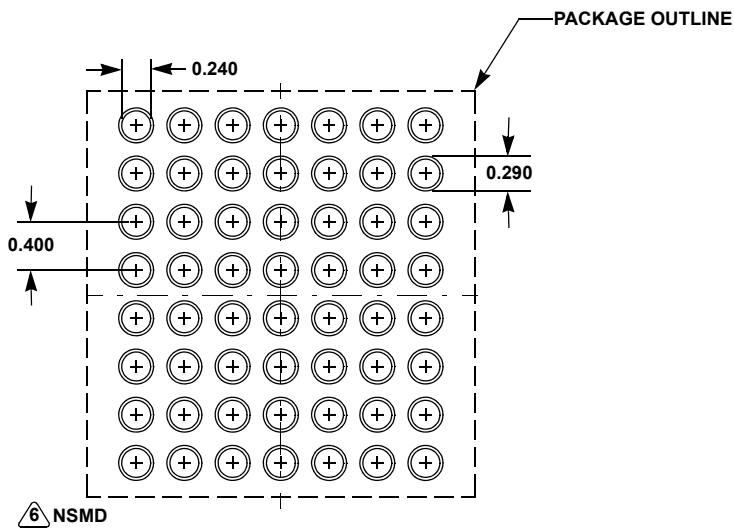
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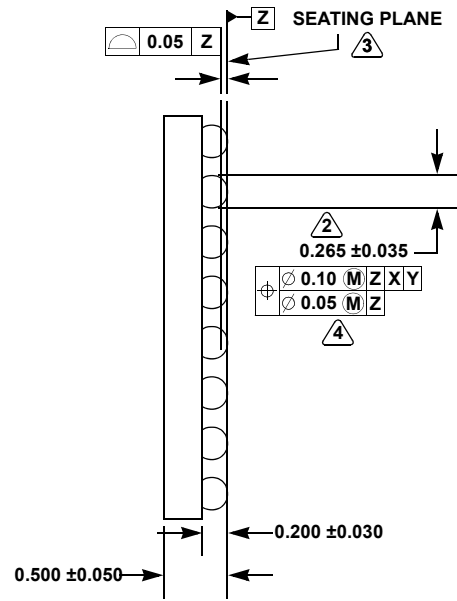
TOP VIEW



BOTTOM VIEW



TYPICAL RECOMMENDED LAND PATTERN



SIDE VIEW

NOTES:

- Dimensions and tolerance per ASME Y 14.5M - 1994.
- Dimension is measured at the maximum bump diameter parallel to primary datum Z .
- Primary datum Z and seating plane are defined by the spherical crowns of the bump.
- Bump position designation per JESD 95-1, SPP-010.
- All dimensions are in millimeters.
- NSMD refers to non-solder mask defined pad design per Intersil Techbrief [TB451](#).